IPC ASSOCIATION CONNECTION ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.										
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materi					rials and M	fg Informat	ion		
upplier Inforn															
Company name*			Company unique ID			τ	Unique ID Authority					Response Date*			
nsemi											2025-07	2025-07-03			
Contact Name			Title - Contact			1	Phone - Contact*				Email - Contact*				
Product-Env-Stew	ards		Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Authorized Representative*			Title - Representative			1	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com				
Request	Requester Item Number Mf		Mfr Item Number Mfr Item Name			Effe		Versio	n I	Manufacturing Site		Weight*	UOM	Unit Type	
		MT9M114EBLSTCZ- 1 MP 1/6 S CR1		1 MP 1/6 SOC CIS	1/6 SOC CIS		2025-07-03 CP2		CP2	27.085 mg		mg	Each		
Ianufacturing	Process Information	on													
Terminal Plating / Grid Array Material T			Terminal Base Alloy J-STD-020 MSI		L Rating	Peak Process Body Temperature Max Time at Pe		k Tempera	ture Numb	er of Reflow Cyc	eles				
SnAgCu		C	CU Alloy 3		1		260	C 30		30	seconds 3				
omments															
TTENTION: MS	L 3 Rated item requires l	Bake and Dr	ry Pack (after	electrical test)											
or more informati	ion regarding material co	omposition p	olease refer to	page 3											

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of						
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	4.09	mg		Misc.	proprietary data		0.0155	mg
			Supplier	Silicon (Si)	7440-21-3		4.034	mg
			Supplier	Aluminum (Al)	7429-90-5		0.0405	mg
Die Attach	0.57	mg	Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.342	mg
			Supplier	Epoxy resins	129915-35-1		0.114	mg
			Supplier	Acrylic resins	Proprietary Data		0.114	mg
Electrode	0.45	mg	Supplier	Titanium (Ti)	7440-32-6		0.0003	mg
			В	Nickel (Ni)	7440-02-0		0.2679	mg
			Supplier	Gold (Au)	7440-57-5		0.0108	mg
			Supplier	Copper (Cu)	7440-50-8		0.0067	mg
			Supplier	Aluminum (Al)	7429-90-5		0.1643	mg
Glass Lid /Cap	19.46	mg	Supplier	Boron Trioxide (B2O3)	1303-86-2		2.7633	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		9.73	mg
			Supplier	Barium Monoxide (BaO)	1304-28-5		4.6704	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		2.1406	mg
			Supplier	Calcium Monoxide (CaO)	1305-78-8		0.0195	mg
			В	Arsenic Trioxide (As2O3)	1327-53-3		0.1362	mg
Lid Attach	0.005	mg		Photoinitiator	proprietary data		0.0012	mg
			Supplier	Epoxy Prepolymer	Proprietary Data		0.0037	mg
Passivation	0.33	mg	Supplier	Pentaerythritol triacrylate	3524-68-3		0.0495	mg
			Supplier	2-(2-methoxypropoxy)propanol	34590-94-8		0.033	mg
			Supplier	Epoxy Phenol Novolak Resin	28064-14-4		0.033	mg
			Supplier	9-Phenylacridine	602-56-2		0.0165	mg
			Supplier	Bisphenol A_Epichlorohydrin Polymer	25068-38-6		0.198	mg
Solder Ball	0.42	mg	Supplier	Silver (Ag)	7440-22-4		0.0126	mg
			Supplier	Tin (Sn)	7440-31-5		0.4053	mg
			Supplier	Copper (Cu)	7440-50-8		0.0021	mg
Substrate and Solder Mask	1.76	mg	Supplier	Silica crystalline	14808-60-7, 14464- 46-1		0.176	mg
			Supplier	Cured Resin of Solder Mask	Proprietary Data		0.836	mg
			Supplier	Bismaleimide Triazine resin	Proprietary Data		0.748	mg